# Inverter

The MC74VHC1G04 is an advanced high speed CMOS inverter fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The MC74VHC1G04 input structure provides protection when voltages up to 7V are applied, regardless of the supply voltage. This allows the MC74VHC1G04 to be used to interface 5V circuits to 3V circuits.

- High Speed: tpD = 3.5ns (Typ) at  $V_{CC} = 5V$
- Low Power Dissipation:  $I_{CC} = 2\mu A$  (Max) at  $T_A = 25$ °C
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300mA
- ESD Performance: HBM > 1500V; MM > 200V

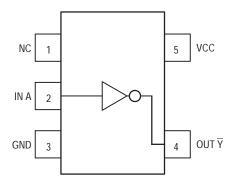


Figure 1. 5-Lead SOT-353 Pinout (Top View)

#### **LOGIC SYMBOL**





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SC-88A / SOT-353 DF SUFFIX CASE 419A

#### **MARKING DIAGRAM**



	PIN ASSIGNMENT							
1	NC							
2	IN A							
3	GND							
4	OUT $\overline{Y}$							
5	VCC							

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

# **FUNCTION TABLE**

A Input	₹ Output
L	Н
Н	L

## **MAXIMUM RATINGS\***

Characteristics	Symbol	Value	Unit
DC Supply Voltage	Vcc	-0.5 to +7.0	V
DC Input Voltage	VIN	-0.5 to +7.0	V
DC Output Voltage V <sub>CC</sub> = 0 High or Low State	Vout	−0.5 to 7.0 −0.5 to V <sub>CC</sub> + 0.5	V
Input Diode Current	lık	-20	mA
Output Diode Current (VOUT < GND; VOUT > VCC)	lok	+20	mA
DC Output Current, per Pin	lout	+25	mA
DC Supply Current, V <sub>CC</sub> and GND	Icc	+50	mA
Power dissipation in still air, SC-88A †	PD	200	mW
Lead temperature, 1 mm from case for 10 s	TL	260	°C
Storage temperature	T <sub>stg</sub>	-65 to +150	°C

<sup>\*</sup> Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

## **RECOMMENDED OPERATING CONDITIONS**

Characteristics	Symbol	Min	Max	Unit
DC Supply Voltage	Vcc	2.0	5.5	V
DC Input Voltage	VIN	0.0	5.5	V
DC Output Voltage	Vout	0.0	Vcc	V
Operating Temperature Range	TA	<b>-</b> 55	+85	°C
Input Rise and Fall Time $V_{CC} = 3.3V \pm 0.3V$ $V_{CC} = 5.0V \pm 0.5V$	t <sub>r</sub> , t <sub>f</sub>	0	100 20	ns/V

<sup>†</sup>Derating — SC-88A Package: -3 mW/°C from 65° to 125°C

#### DC ELECTRICAL CHARACTERISTICS

			VCC	Т	T <sub>A</sub> = 25°C		T <sub>A</sub> ≤	85°C	<b>T</b> <sub>A</sub> ≤ '	125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	Minimum High–Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V <sub>IL</sub>	Maximum Low–Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65	V
VOH	Minimum High–Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -50μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -4mA I <sub>OH</sub> = -8mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
VOL	Maximum Low–Level Output Voltage VIN = VIH or VIL	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 50μA	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 4mA I <sub>OL</sub> = 8mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	V
IN	Maximum Input Leakage Current	V <sub>IN</sub> = 5.5V or GND	0 to 5.5			±0.1		±1.0		±1.0	μА
lcc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			2.0		20		40	μА

# AC ELECTRICAL CHARACTERISTICS ( $C_{load}$ = 50 pF, Input $t_r$ = $t_f$ = 3.0ns)

				T <sub>A</sub> = 25°C		;	T <sub>A</sub> ≤ 85°C		<b>T</b> <sub>A</sub> ≤ 125°C		
Symbol	Parameter	Test Conditions		Min	Тур	Max	Min	Max	Min	Max	Unit
tPLH, tPHL	Maximum Propogation Delay,	$V_{CC} = 3.0 \pm 0.3 V$	$C_L = 15 pF$ $C_L = 50 pF$		4.5 6.4	7.1 10.6		8.5 12.0		10.0 14.5	ns
	Input A to $\overline{Y}$	$V_{CC} = 5.0 \pm 0.5 V$	$C_L = 15 pF$ $C_L = 50 pF$		3.5 4.5	5.5 7.5		6.5 8.5		8.0 10.0	
C <sub>IN</sub>	Maximum Input Capacitance				4	10		10		10	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0V	
$C_{PD}$	Power Dissipation Capacitance (Note 1.)	8.0	pF

<sup>1.</sup> CPD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: ICC(OPR) = CPD • VCC • f<sub>in</sub> + I<sub>CC</sub>. CPD is used to determine the no–load dynamic power consumption; PD = CPD • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

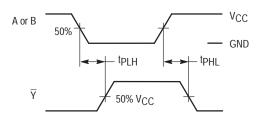
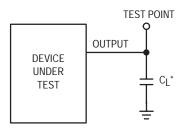


Figure 2. Switching Waveforms



\*Includes all probe and jig capacitance

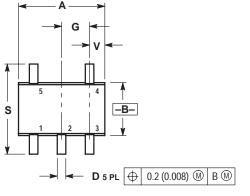
Figure 3. Test Circuit

## **DEVICE ORDERING INFORMATION**

Device Order Number	Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package Type	Tape and Reel Size
MC74VHC1G04DFT1	MC	74	VHC1G	04	DF	T1	SC-88A / SOT-353	7–Inch/3000 Unit

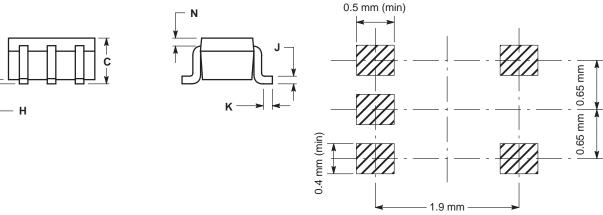
## **PACKAGE DIMENSIONS**

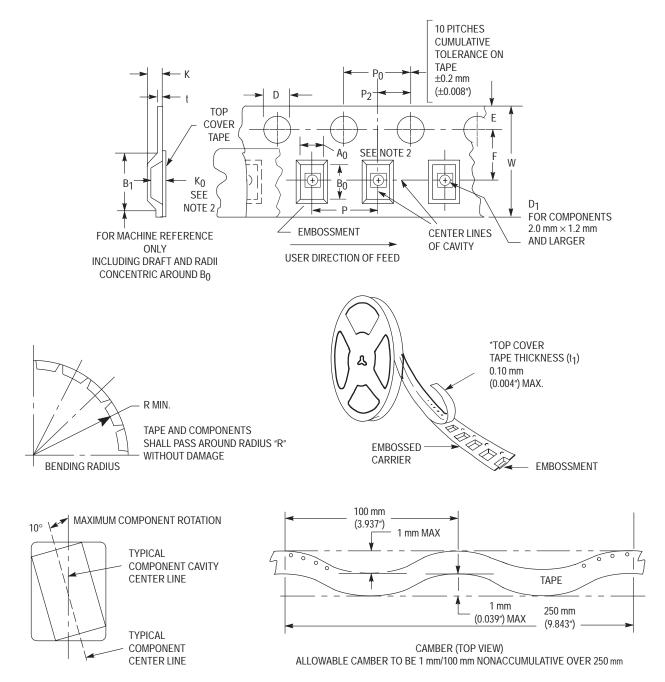
SC-88A / SOT-353 **DF SUFFIX** 5-LEAD PACKAGE CASE 419A-01 **ISSUE B** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MM.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.004 0.012		0.30	
N	0.008	REF	0.20	REF	
S	0.079	0.087	2.00	2.20	
V	0.012	0.016	0.30	0.40	





**Figure 4. Carrier Tape Specifications** 

### EMBOSSED CARRIER DIMENSIONS (See Notes 1 and 2)

Tape Size	B <sub>1</sub> Max	D	D <sub>1</sub>	E	F	К	Р	P <sub>0</sub>	P <sub>2</sub>	R	Т	w
8 mm	4.35 mm (0.171")	1.5 +0.1/ -0.0 mm (0.059 +0.004/ -0.0")	1.0 mm Min (0.039")	1.75 ±0.1 mm (0.069 ±0.004")	3.5 ±0.5 mm (1.38 ±0.002")	2.4 mm (0.094")	4.0 ±0.10 mm (0.157 ±0.004")	4.0 ±0.1 mm (0.156 ±0.004")	2.0 ±0.1 mm (0.079 ±0.002")	25 mm (0.98")	0.3 ±0.05 mm (0.01 +0.0038/ -0.0002")	8.0 ±0.3 mm (0.315 ±0.012")

Metric Dimensions Govern–English are in parentheses for reference only.
 A<sub>0</sub>, B<sub>0</sub>, and K<sub>0</sub> are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

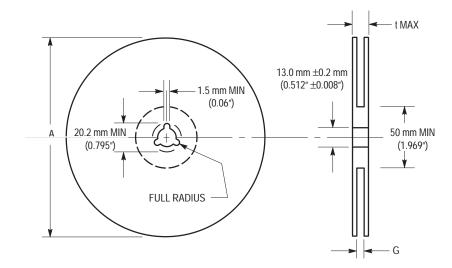


Figure 5. Reel Dimensions

# **REEL DIMENSIONS**

Tape Size	A Max	G	t Max
8 mm	330 mm	8.400 mm, +1.5 mm, -0.0	14.4 mm
	(13")	(0.33", +0.059", -0.00)	(0.56")

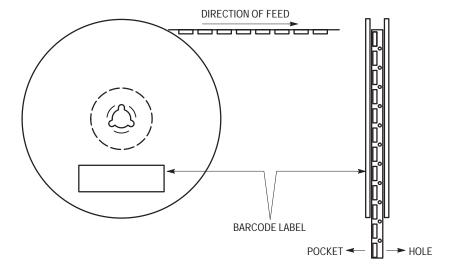


Figure 6. Reel Winding Direction

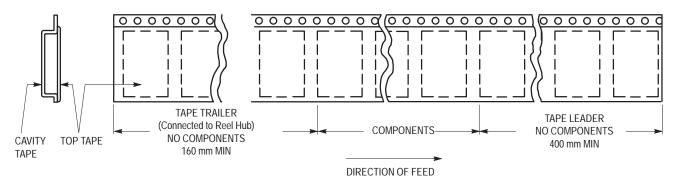


Figure 7. Tape Ends for Finished Goods

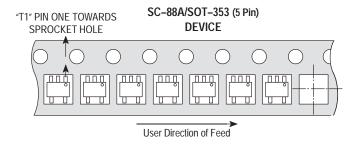


Figure 8. Reel Configuration

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